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Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I ² C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	22
Program Memory Size	14KB (8K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	368 x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 6V
Data Converters	A/D 5x8b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	28-DIP (0.300", 7.62mm)
Supplier Device Package	28-SPDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c76-20i-sp

PIC16C7X

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For register and module descriptions in this data sheet, device legends show which devices apply to those sections. As an example, the legend below would mean that the following section applies only to the PIC16C72, PIC16C73A and PIC16C74A devices.

Applicable Devices						
72	73	73A	74	74A	76	77

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NOTES:

FIGURE 4-4: PIC16C72 REGISTER FILE MAP


File Address			File Address
00h	INDF ⁽¹⁾	INDF ⁽¹⁾	80h
01h	TMR0	OPTION	81h
02h	PCL	PCL	82h
03h	STATUS	STATUS	83h
04h	FSR	FSR	84h
05h	PORTA	TRISA	85h
06h	PORTB	TRISB	86h
07h	PORTC	TRISC	87h
08h			88h
09h			89h
0Ah	PCLATH	PCLATH	8Ah
0Bh	INTCON	INTCON	8Bh
0Ch	PIR1	PIE1	8Ch
0Dh			8Dh
0Eh	TMR1L	PCON	8Eh
0Fh	TMR1H		8Fh
10h	T1CON		90h
11h	TMR2		91h
12h	T2CON	PR2	92h
13h	SSPBUF	SSPADDD	93h
14h	SSPCON	SSPSTAT	94h
15h	CCPR1L		95h
16h	CCPR1H		96h
17h	CCP1CON		97h
18h			98h
19h			99h
1Ah			9Ah
1Bh			9Bh
1Ch			9Ch
1Dh			9Dh
1Eh	ADRES		9Eh
1Fh	ADCON0	ADCON1	9Fh
20h	General Purpose Register	General Purpose Register	A0h
			BFh
			C0h
7Fh	Bank 0	Bank 1	FFh

Unimplemented data memory locations, read as '0'.

Note 1: Not a physical register.

FIGURE 4-5: PIC16C73/73A/74/74A REGISTER FILE MAP

File Address			File Address
00h	INDF ⁽¹⁾	INDF ⁽¹⁾	80h
01h	TMR0	OPTION	81h
02h	PCL	PCL	82h
03h	STATUS	STATUS	83h
04h	FSR	FSR	84h
05h	PORTA	TRISA	85h
06h	PORTB	TRISB	86h
07h	PORTC	TRISC	87h
08h	PORTD ⁽²⁾	TRISD ⁽²⁾	88h
09h	PORTE ⁽²⁾	TRISE ⁽²⁾	89h
0Ah	PCLATH	PCLATH	8Ah
0Bh	INTCON	INTCON	8Bh
0Ch	PIR1	PIE1	8Ch
0Dh	PIR2	PIE2	8Dh
0Eh	TMR1L	PCON	8Eh
0Fh	TMR1H		8Fh
10h	T1CON		90h
11h	TMR2		91h
12h	T2CON	PR2	92h
13h	SSPBUF	SSPADD	93h
14h	SSPCON	SSPSTAT	94h
15h	CCPR1L		95h
16h	CCPR1H		96h
17h	CCP1CON		97h
18h	RCSTA	TXSTA	98h
19h	TXREG	SPBRG	99h
1Ah	RCREG		9Ah
1Bh	CCPR2L		9Bh
1Ch	CCPR2H		9Ch
1Dh	CCP2CON		9Dh
1Eh	ADRES		9Eh
1Fh	ADCON0	ADCON1	9Fh
20h			A0h
	General Purpose Register	General Purpose Register	
7Fh			FFh
	Bank 0	Bank 1	

 Unimplemented data memory locations, read as '0'.

Note 1: Not a physical register.
 Note 2: These registers are not physically implemented on the PIC16C73/73A, read as '0'.

PIC16C7X

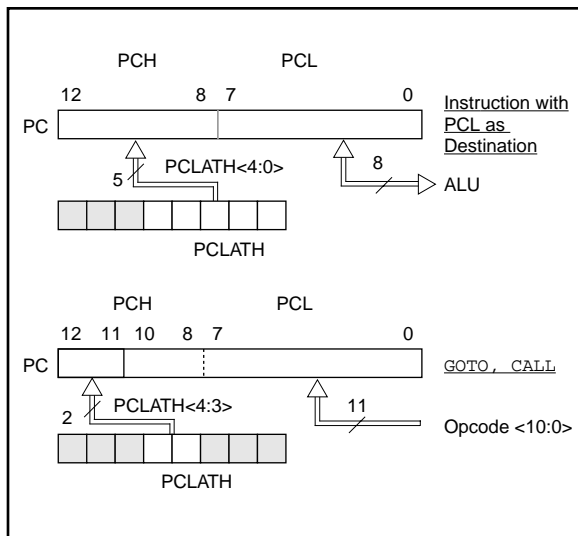
4.3 PCL and PCLATH

Applicable Devices

72	73	73A	74	74A	76	77
----	----	-----	----	-----	----	----

The program counter (PC) is 13-bits wide. The low byte comes from the PCL register, which is a readable and writable register. The upper bits (PC<12:8>) are not readable, but are indirectly writable through the PCLATH register. On any reset, the upper bits of the PC will be cleared. Figure 4-17 shows the two situations for the loading of the PC. The upper example in the figure shows how the PC is loaded on a write to PCL (PCLATH<4:0> → PCH). The lower example in the figure shows how the PC is loaded during a CALL or GOTO instruction (PCLATH<4:3> → PCH).

FIGURE 4-17: LOADING OF PC IN DIFFERENT SITUATIONS



4.3.1 COMPUTED GOTO

A computed GOTO is accomplished by adding an offset to the program counter (`ADDWF PCL`). When doing a table read using a computed GOTO method, care should be exercised if the table location crosses a PCL memory boundary (each 256 byte block). Refer to the application note "Implementing a Table Read" (AN556).

4.3.2 STACK

The PIC16CXX family has an 8 level deep x 13-bit wide hardware stack. The stack space is not part of either program or data space and the stack pointer is not readable or writable. The PC is PUSHed onto the stack when a CALL instruction is executed or an interrupt causes a branch. The stack is POPed in the event of a RETURN, RETLW or a RETFIE instruction execution. PCLATH is not affected by a PUSH or POP operation.

The stack operates as a circular buffer. This means that after the stack has been PUSHed eight times, the ninth push overwrites the value that was stored from the first push. The tenth push overwrites the second push (and so on).

Note 1: There are no status bits to indicate stack overflow or stack underflow conditions.

Note 2: There are no instructions/mnemonics called PUSH or POP. These are actions that occur from the execution of the CALL, RETURN, RETLW, and RETFIE instructions, or the vectoring to an interrupt address.

4.4 Program Memory Paging

Applicable Devices

72	73	73A	74	74A	76	77
----	----	-----	----	-----	----	----

PIC16C7X devices are capable of addressing a continuous 8K word block of program memory. The CALL and GOTO instructions provide only 11 bits of address to allow branching within any 2K program memory page. When doing a CALL or GOTO instruction the upper 2 bits of the address are provided by PCLATH<4:3>. When doing a CALL or GOTO instruction, the user must ensure that the page select bits are programmed so that the desired program memory page is addressed. If a return from a CALL instruction (or interrupt) is executed, the entire 13-bit PC is pushed onto the stack. Therefore, manipulation of the PCLATH<4:3> bits are not required for the return instructions (which POPs the address from the stack).

Note: PIC16C7X devices with 4K or less of program memory ignore paging bit PCLATH<4>. The use of PCLATH<4> as a general purpose read/write bit is not recommended since this may affect upward compatibility with future products.

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TABLE 5-1: PORTA FUNCTIONS

Name	Bit#	Buffer	Function
RA0/AN0	bit0	TTL	Input/output or analog input
RA1/AN1	bit1	TTL	Input/output or analog input
RA2/AN2	bit2	TTL	Input/output or analog input
RA3/AN3/VREF	bit3	TTL	Input/output or analog input or VREF
RA4/T0CKI	bit4	ST	Input/output or external clock input for Timer0 Output is open drain type
RA5/ \overline{SS} /AN4	bit5	TTL	Input/output or slave select input for synchronous serial port or analog input

Legend: TTL = TTL input, ST = Schmitt Trigger input

TABLE 5-2: SUMMARY OF REGISTERS ASSOCIATED WITH PORTA

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets
05h	PORTA	—	—	RA5	RA4	RA3	RA2	RA1	RA0	--0x 0000	--0u 0000
85h	TRISA	—	—	PORTA Data Direction Register						--11 1111	--11 1111
9Fh	ADCON1	—	—	—	—	—	PCFG2	PCFG1	PCFG0	---- -000	---- -000

Legend: x = unknown, u = unchanged, - = unimplemented locations read as '0'. Shaded cells are not used by PORTA.

5.2 PORTB and TRISB Registers

Applicable Devices					
72	73	73A	74	74A	76/77

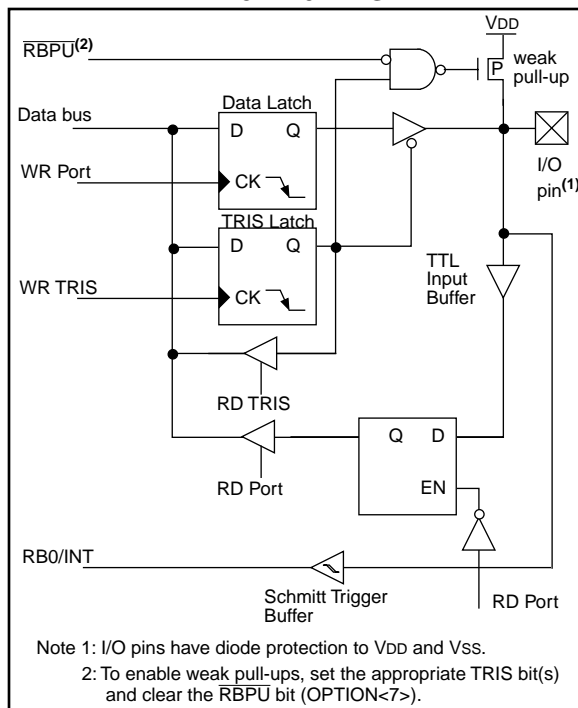
PORTB is an 8-bit wide bi-directional port. The corresponding data direction register is TRISB. Setting a bit in the TRISB register puts the corresponding output driver in a hi-impedance input mode. Clearing a bit in the TRISB register puts the contents of the output latch on the selected pin(s).

EXAMPLE 5-2: INITIALIZING PORTB

```
BCF    STATUS, RP0    ;
CLRF   PORTB          ; Initialize PORTB by
                     ; clearing output
                     ; data latches
BSF    STATUS, RP0    ; Select Bank 1
MOVLW  0xCF           ; Value used to
                     ; initialize data
                     ; direction
MOVWF  TRISB          ; Set RB<3:0> as inputs
                     ; RB<5:4> as outputs
                     ; RB<7:6> as inputs
```

Each of the PORTB pins has a weak internal pull-up. A single control bit can turn on all the pull-ups. This is performed by clearing bit RBP_U (OPTION<7>). The weak pull-up is automatically turned off when the port pin is configured as an output. The pull-ups are disabled on a Power-on Reset.

FIGURE 5-3: BLOCK DIAGRAM OF RB3:RB0 PINS



Four of PORTB's pins, RB7:RB4, have an interrupt on change feature. Only pins configured as inputs can cause this interrupt to occur (i.e. any RB7:RB4 pin configured as an output is excluded from the interrupt on change comparison). The input pins (of RB7:RB4) are compared with the old value latched on the last read of PORTB. The "mismatch" outputs of RB7:RB4 are OR'ed together to generate the RB Port Change Interrupt with flag bit RBIF (INTCON<0>).

This interrupt can wake the device from SLEEP. The user, in the interrupt service routine, can clear the interrupt in the following manner:

- Any read or write of PORTB. This will end the mismatch condition.
- Clear flag bit RBIF.

A mismatch condition will continue to set flag bit RBIF. Reading PORTB will end the mismatch condition, and allow flag bit RBIF to be cleared.

This interrupt on mismatch feature, together with software configurable pull-ups on these four pins allow easy interface to a keypad and make it possible for wake-up on key-depression. Refer to the Embedded Control Handbook, "Implementing Wake-Up on Key Stroke" (AN552).

Note: For the PIC16C73/74, if a change on the I/O pin should occur when the read operation is being executed (start of the Q2 cycle), then interrupt flag bit RBIF may not get set.

The interrupt on change feature is recommended for wake-up on key depression operation and operations where PORTB is only used for the interrupt on change feature. Polling of PORTB is not recommended while using the interrupt on change feature.

7.3.1 SWITCHING PRESCALER ASSIGNMENT

The prescaler assignment is fully under software control, i.e., it can be changed “on the fly” during program execution.

Note: To avoid an unintended device RESET, the following instruction sequence (shown in Example 7-1) must be executed when changing the prescaler assignment from Timer0 to the WDT. This sequence must be followed even if the WDT is disabled.

EXAMPLE 7-1: CHANGING PRESCALER (TIMER0→WDT)

```

1) BSF    STATUS, RP0    ;Bank 1
Lines 2 and 3 do NOT have to 2) MOVLW    b'xx0x0xxx'    ;Select clock source and prescale value of
be included if the final desired 3) MOVWF    OPTION_REG    ;other than 1:1
prescale value is other than 1:1. 4) BCF     STATUS, RP0    ;Bank 0
If 1:1 is final desired value, then 5) CLRF     TMR0          ;Clear TMR0 and prescaler
a temporary prescale value is 6) BSF     STATUS, RP1    ;Bank 1
set in lines 2 and 3 and the final 7) MOVLW    b'xxxx1xxx'    ;Select WDT, do not change prescale value
prescale value will be set in lines 8) MOVWF    OPTION_REG    ;
10 and 11. 9) CLRWDT          ;Clears WDT and prescaler
10) MOVLW    b'xxxx1xxx'    ;Select new prescale value and WDT
11) MOVWF    OPTION_REG    ;
12) BCF     STATUS, RP0    ;Bank 0

```

To change prescaler from the WDT to the Timer0 module use the sequence shown in Example 7-2.

EXAMPLE 7-2: CHANGING PRESCALER (WDT→TIMER0)

```

CLRWDT          ;Clear WDT and prescaler
BSF    STATUS, RP0 ;Bank 1
MOVLW    b'xxx0xxx' ;Select TMR0, new prescale value and
MOVWF    OPTION_REG ;clock source
BCF     STATUS, RP0 ;Bank 0

```

TABLE 7-1: REGISTERS ASSOCIATED WITH TIMER0

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets
01h,101h	TMR0	Timer0 module's register								xxxx xxxx	uuuu uuuu
0Bh,8Bh, 10Bh,18Bh	INTCON	GIE	PEIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000 000x	0000 000u
81h,181h	OPTION	RBP _U	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
85h	TRISA	—	—	PORTA Data Direction Register						--11 1111	--11 1111

Legend: x = unknown, u = unchanged, - = unimplemented locations read as '0'. Shaded cells are not used by Timer0.

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TABLE 10-5: REGISTERS ASSOCIATED WITH PWM AND TIMER2

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets
0Bh,8Bh, 10Bh,18Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	PSPIF ^(1,2)	ADIF	RCIF ⁽²⁾	TXIF ⁽²⁾	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
0Dh ⁽²⁾	PIR2	—	—	—	—	—	—	—	CCP2IF	---- --0	---- --0
8Ch	PIE1	PSPIE ^(1,2)	ADIE	RCIE ⁽²⁾	TXIE ⁽²⁾	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
8Dh ⁽²⁾	PIE2	—	—	—	—	—	—	—	CCP2IE	---- --0	---- --0
87h	TRISC	PORTC Data Direction Register								1111 1111	1111 1111
11h	TMR2	Timer2 module's register								0000 0000	0000 0000
92h	PR2	Timer2 module's period register								1111 1111	1111 1111
12h	T2CON	—	TOUTPS3	TOUTPS2	TOUTPS1	TOUTPS0	TMR2ON	T2CKPS1	T2CKPS0	-000 0000	-000 0000
15h	CCPR1L	Capture/Compare/PWM register1 (LSB)								xxxx xxxx	uuuu uuuu
16h	CCPR1H	Capture/Compare/PWM register1 (MSB)								xxxx xxxx	uuuu uuuu
17h	CCP1CON	—	—	CCP1X	CCP1Y	CCP1M3	CCP1M2	CCP1M1	CCP1M0	--00 0000	--00 0000
1Bh ⁽²⁾	CCPR2L	Capture/Compare/PWM register2 (LSB)								xxxx xxxx	uuuu uuuu
1Ch ⁽²⁾	CCPR2H	Capture/Compare/PWM register2 (MSB)								xxxx xxxx	uuuu uuuu
1Dh ⁽²⁾	CCP2CON	—	—	CCP2X	CCP2Y	CCP2M3	CCP2M2	CCP2M1	CCP2M0	--00 0000	--00 0000

Legend: x = unknown, u = unchanged, - = unimplemented read as '0'. Shaded cells are not used by PWM and Timer2.

Note 1: Bits PSPIE and PSPIF are reserved on the PIC16C73/73A/76, always maintain these bits clear.

2: The PIC16C72 does not have a Parallel Slave Port, USART or CCP2 module, these bits are unimplemented, read as '0'.

12.3 USART Synchronous Master Mode

Applicable Devices							
72	73	73A	74	74A	76	77	

In Synchronous Master mode, the data is transmitted in a half-duplex manner i.e. transmission and reception do not occur at the same time. When transmitting data, the reception is inhibited and vice versa. Synchronous mode is entered by setting bit SYNC (TXSTA<4>). In addition enable bit SPEN (RCSTA<7>) is set in order to configure the RC6/TX/CK and RC7/RX/DT I/O pins to CK (clock) and DT (data) lines respectively. The Master mode indicates that the processor transmits the master clock on the CK line. The Master mode is entered by setting bit CSRC (TXSTA<7>).

12.3.1 USART SYNCHRONOUS MASTER TRANSMISSION

The USART transmitter block diagram is shown in Figure 12-7. The heart of the transmitter is the transmit (serial) shift register (TSR). The shift register obtains its data from the read/write transmit buffer register TXREG. The TXREG register is loaded with data in software. The TSR register is not loaded until the last bit has been transmitted from the previous load. As soon as the last bit is transmitted, the TSR is loaded with new data from the TXREG (if available). Once the TXREG register transfers the data to the TSR register (occurs in one Tcycle), the TXREG is empty and interrupt bit, TXIF (PIR1<4>) is set. The interrupt can be enabled/disabled by setting/clearing enable bit TXIE (PIE1<4>). Flag bit TXIF will be set regardless of the state of enable bit TXIE and cannot be cleared in software. It will reset only when new data is loaded into the TXREG register. While flag bit TXIF indicates the status of the TXREG register, another bit TRMT (TXSTA<1>) shows the status of the TSR register. TRMT is a read only bit which is set when the TSR is empty. No interrupt logic is tied to this bit, so the user has to poll this bit in order to determine if the TSR register is empty. The TSR is not mapped in data memory so it is not available to the user.

Transmission is enabled by setting enable bit TXEN (TXSTA<5>). The actual transmission will not occur until the TXREG register has been loaded with data. The first data bit will be shifted out on the next available rising edge of the clock on the CK line. Data out is stable around the falling edge of the synchronous clock (Figure 12-12). The transmission can also be started by first loading the TXREG register and then setting bit TXEN (Figure 12-13). This is advantageous when slow baud rates are selected, since the BRG is kept in reset when bits TXEN, CREN, and SREN are clear. Setting enable bit TXEN will start the BRG, creating a shift clock immediately. Normally when transmission is first started, the TSR register is empty, so a transfer to the TXREG register will result in an immediate transfer to TSR resulting in an empty TXREG. Back-to-back transfers are possible.

Clearing enable bit TXEN, during a transmission, will cause the transmission to be aborted and will reset the transmitter. The DT and CK pins will revert to hi-impedance. If either bit CREN or bit SREN is set, during a transmission, the transmission is aborted and the DT pin reverts to a hi-impedance state (for a reception). The CK pin will remain an output if bit CSRC is set (internal clock). The transmitter logic however is not reset although it is disconnected from the pins. In order to reset the transmitter, the user has to clear bit TXEN. If bit SREN is set (to interrupt an on-going transmission and receive a single word), then after the single word is received, bit SREN will be cleared and the serial port will revert back to transmitting since bit TXEN is still set. The DT line will immediately switch from hi-impedance receive mode to transmit and start driving. To avoid this, bit TXEN should be cleared.

In order to select 9-bit transmission, the TX9 (TXSTA<6>) bit should be set and the ninth bit should be written to bit TX9D (TXSTA<0>). The ninth bit must be written before writing the 8-bit data to the TXREG register. This is because a data write to the TXREG can result in an immediate transfer of the data to the TSR register (if the TSR is empty). If the TSR was empty and the TXREG was written before writing the "new" TX9D, the "present" value of bit TX9D is loaded.

Steps to follow when setting up a Synchronous Master Transmission:

1. Initialize the SPBRG register for the appropriate baud rate (Section 12.1).
2. Enable the synchronous master serial port by setting bits SYNC, SPEN, and CSRC.
3. If interrupts are desired, then set enable bit TXIE.
4. If 9-bit transmission is desired, then set bit TX9.
5. Enable the transmission by setting bit TXEN.
6. If 9-bit transmission is selected, the ninth bit should be loaded in bit TX9D.
7. Start transmission by loading data to the TXREG register.

13.5 A/D Operation During Sleep

Applicable Devices

72	73	73A	74	74A	76	77
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The A/D module can operate during SLEEP mode. This requires that the A/D clock source be set to RC (ADCS1:ADCS0 = 11). When the RC clock source is selected, the A/D module waits one instruction cycle before starting the conversion. This allows the SLEEP instruction to be executed, which eliminates all digital switching noise from the conversion. When the conversion is completed the GO/DONE bit will be cleared, and the result loaded into the ADRES register. If the A/D interrupt is enabled, the device will wake-up from SLEEP. If the A/D interrupt is not enabled, the A/D module will then be turned off, although the ADON bit will remain set.

When the A/D clock source is another clock option (not RC), a SLEEP instruction will cause the present conversion to be aborted and the A/D module to be turned off, though the ADON bit will remain set.

Turning off the A/D places the A/D module in its lowest current consumption state.

Note: For the A/D module to operate in SLEEP, the A/D clock source must be set to RC (ADCS1:ADCS0 = 11). To perform an A/D conversion in SLEEP, ensure the SLEEP instruction immediately follows the instruction that sets the GO/DONE bit.

13.6 A/D Accuracy/Error

Applicable Devices

72	73	73A	74	74A	76	77
----	----	-----	----	-----	----	----

The absolute accuracy specified for the A/D converter includes the sum of all contributions for quantization error, integral error, differential error, full scale error, offset error, and monotonicity. It is defined as the maximum deviation from an actual transition versus an ideal transition for any code. The absolute error of the A/D converter is specified at ± 1 LSB for $V_{DD} = V_{REF}$ (over the device's specified operating range). However, the accuracy of the A/D converter will degrade as V_{DD} diverges from V_{REF} .

For a given range of analog inputs, the output digital code will be the same. This is due to the quantization of the analog input to a digital code. Quantization error is typically $\pm 1/2$ LSB and is inherent in the analog to digital conversion process. The only way to reduce quantization error is to increase the resolution of the A/D converter.

Offset error measures the first actual transition of a code versus the first ideal transition of a code. Offset error shifts the entire transfer function. Offset error can be calibrated out of a system or introduced into a system through the interaction of the total leakage current and source impedance at the analog input.

Gain error measures the maximum deviation of the last actual transition and the last ideal transition adjusted for offset error. This error appears as a change in slope of the transfer function. The difference in gain error to full scale error is that full scale does not take offset error into account. Gain error can be calibrated out in software.

Linearity error refers to the uniformity of the code changes. Linearity errors cannot be calibrated out of the system. Integral non-linearity error measures the actual code transition versus the ideal code transition adjusted by the gain error for each code.

Differential non-linearity measures the maximum actual code width versus the ideal code width. This measure is unadjusted.

The maximum pin leakage current is $\pm 1 \mu A$.

In systems where the device frequency is low, use of the A/D RC clock is preferred. At moderate to high frequencies, TAD should be derived from the device oscillator. TAD must not violate the minimum and should be $\leq 8 \mu s$ for preferred operation. This is because TAD, when derived from TOSC, is kept away from on-chip phase clock transitions. This reduces, to a large extent, the effects of digital switching noise. This is not possible with the RC derived clock. The loss of accuracy due to digital switching noise can be significant if many I/O pins are active.

In systems where the device will enter SLEEP mode after the start of the A/D conversion, the RC clock source selection is required. In this mode, the digital noise from the modules in SLEEP are stopped. This method gives high accuracy.

13.7 Effects of a RESET

Applicable Devices

72	73	73A	74	74A	76	77
----	----	-----	----	-----	----	----

A device reset forces all registers to their reset state. This forces the A/D module to be turned off, and any conversion is aborted.

The value that is in the ADRES register is not modified for a Power-on Reset. The ADRES register will contain unknown data after a Power-on Reset.

FIGURE 14-10: TIME-OUT SEQUENCE ON POWER-UP ($\overline{\text{MCLR}}$ NOT TIED TO V_{DD}): CASE 1

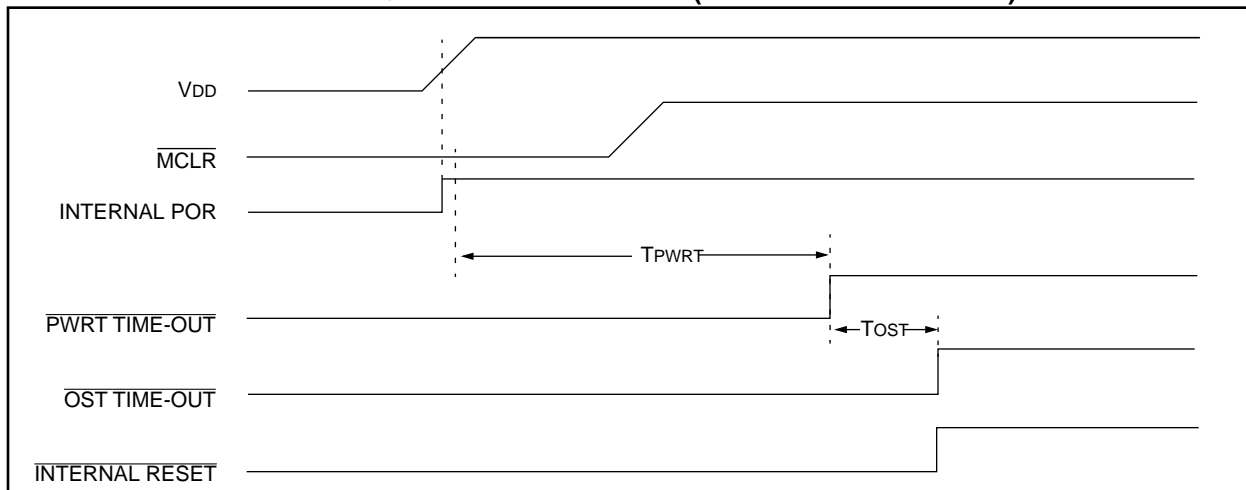


FIGURE 14-11: TIME-OUT SEQUENCE ON POWER-UP ($\overline{\text{MCLR}}$ NOT TIED TO V_{DD}): CASE 2

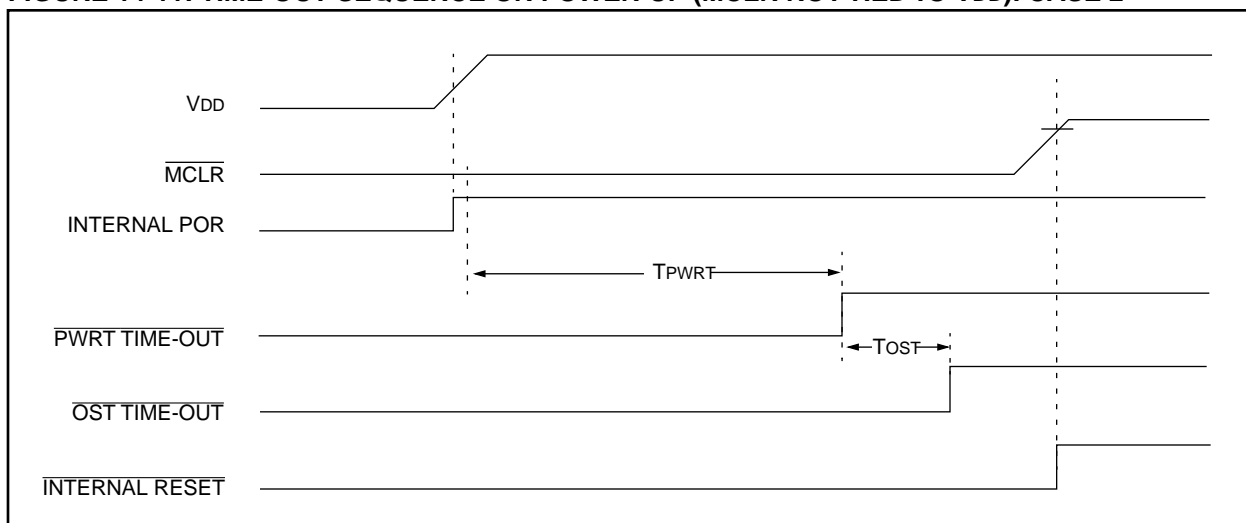
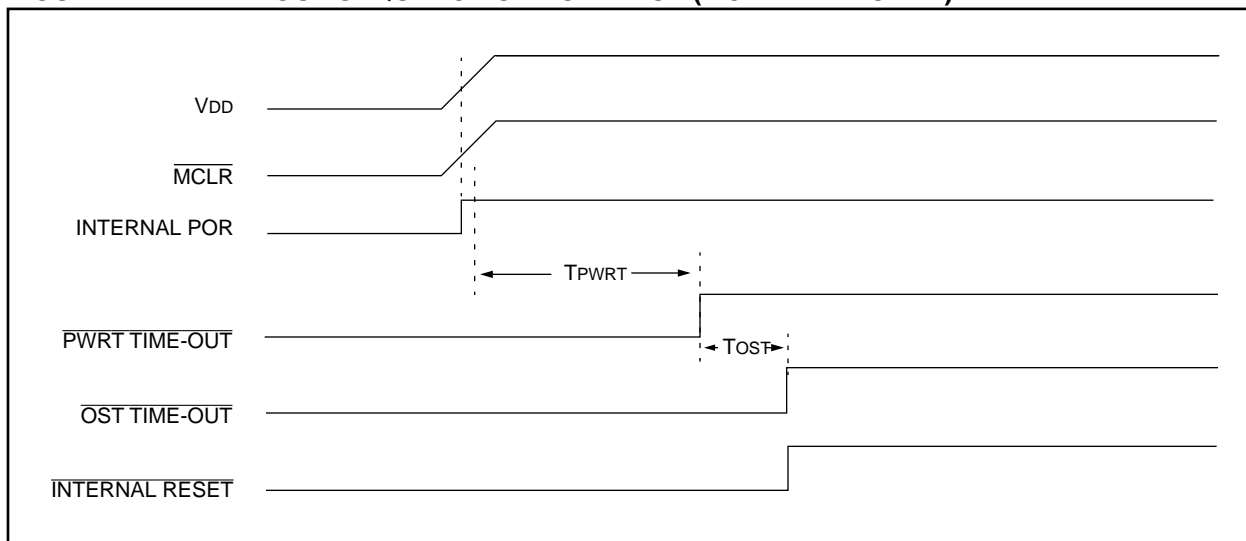


FIGURE 14-12: TIME-OUT SEQUENCE ON POWER-UP ($\overline{\text{MCLR}}$ TIED TO V_{DD})



NOP		No Operation			
Syntax:	[<i>label</i>] NOP				
Operands:	None				
Operation:	No operation				
Status Affected:	None				
Encoding:	00	0000	0xx0	0000	
Description:	No operation.				
Words:	1				
Cycles:	1				
Q Cycle Activity:	Q1	Q2	Q3	Q4	
	Decode	No-Operation	No-Operation	No-Operation	
Example	NOP				

RETFIE		Return from Interrupt								
Syntax:	[<i>label</i>] RETFIE									
Operands:	None									
Operation:	TOS → PC, 1 → GIE									
Status Affected:	None									
Encoding:	00				0000	0000	1001			
Description:	Return from Interrupt. Stack is POPed and Top of Stack (TOS) is loaded in the PC. Interrupts are enabled by setting Global Interrupt Enable bit, GIE (INTCON<7>). This is a two cycle instruction.									
Words:	1									
Cycles:	2									
Q Cycle Activity:	Q1				Q2		Q3		Q4	
1st Cycle	Decode		No-Operation		Set the GIE bit		Pop from the Stack			
2nd Cycle	No-Operation		No-Operation		No-Operation		No-Operation			

Example

```

RETFIE
After Interrupt
    PC =  TOS
    GIE =  1

```

OPTION	Load Option Register			
Syntax:	[<i>label</i>] OPTION			
Operands:	None			
Operation:	(W) → OPTION			
Status Affected:	None			
Encoding:	00	0000	0110	0010
Description:	The contents of the W register are loaded in the OPTION register. This instruction is supported for code compatibility with PIC16C5X products. Since OPTION is a readable/writable register, the user can directly address it.			
Words:	1			
Cycles:	1			
Example	<div>To maintain upward compatibility with future PIC16CXX products, do not use this instruction.</div>			

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XORLW Exclusive OR Literal with W

Syntax: `[label] XORLW k`

Operands: $0 \leq k \leq 255$

Operation: $(W) .XOR. k \rightarrow (W)$

Status Affected: Z

Encoding:

11	1010	kkkk	kkkk
----	------	------	------

Description: The contents of the W register are XOR'ed with the eight bit literal 'k'. The result is placed in the W register.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'	Process data	Write to W

Example: `XORLW 0xAF`
Before Instruction
W = 0xB5
After Instruction
W = 0x1A

XORWF Exclusive OR W with f

Syntax: `[label] XORWF f,d`

Operands: $0 \leq f \leq 127$
 $d \in [0,1]$

Operation: $(W) .XOR. (f) \rightarrow (\text{destination})$

Status Affected: Z

Encoding:

00	0110	dfff	ffff
----	------	------	------

Description: Exclusive OR the contents of the W register with register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process data	Write to destination

Example `XORWF REG 1`
Before Instruction
REG = 0xAF
W = 0xB5
After Instruction
REG = 0x1A
W = 0xB5

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Applicable Devices 72 73 73A 74 74A 76 77

FIGURE 18-11: USART SYNCHRONOUS TRANSMISSION (MASTER/SLAVE) TIMING

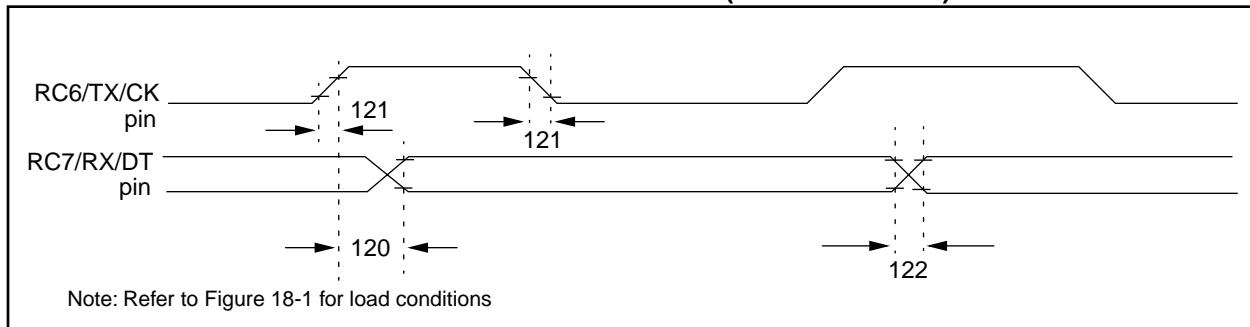


TABLE 18-11: USART SYNCHRONOUS TRANSMISSION REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
120	TckH2dtV	SYNC XMIT (MASTER & SLAVE) Clock high to data out valid	—	—	80	ns	
					100	ns	
121	Tckrf	Clock out rise time and fall time (Master Mode)	—	—	45	ns	
					50	ns	
122	TdtVf	Data out rise time and fall time	—	—	45	ns	
					50	ns	

†: Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 18-12: USART SYNCHRONOUS RECEIVE (MASTER/SLAVE) TIMING

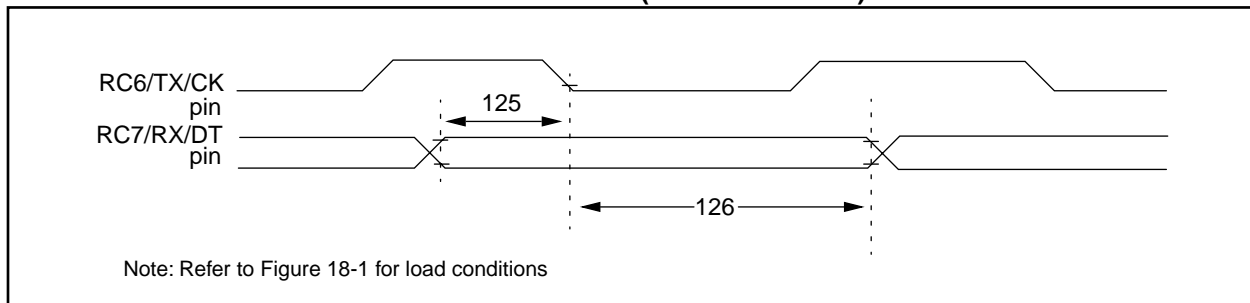


TABLE 18-12: USART SYNCHRONOUS RECEIVE REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
125	TdtV2ckL	SYNC RCV (MASTER & SLAVE) Data setup before CK ↓ (DT setup time)	15	—	—	ns	
126	TckL2dtH	Data hold after CK ↓ (DT hold time)	15	—	—	ns	

†: Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

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Applicable Devices 72 73 73A 74 74A 76 77

FIGURE 18-13: A/D CONVERSION TIMING

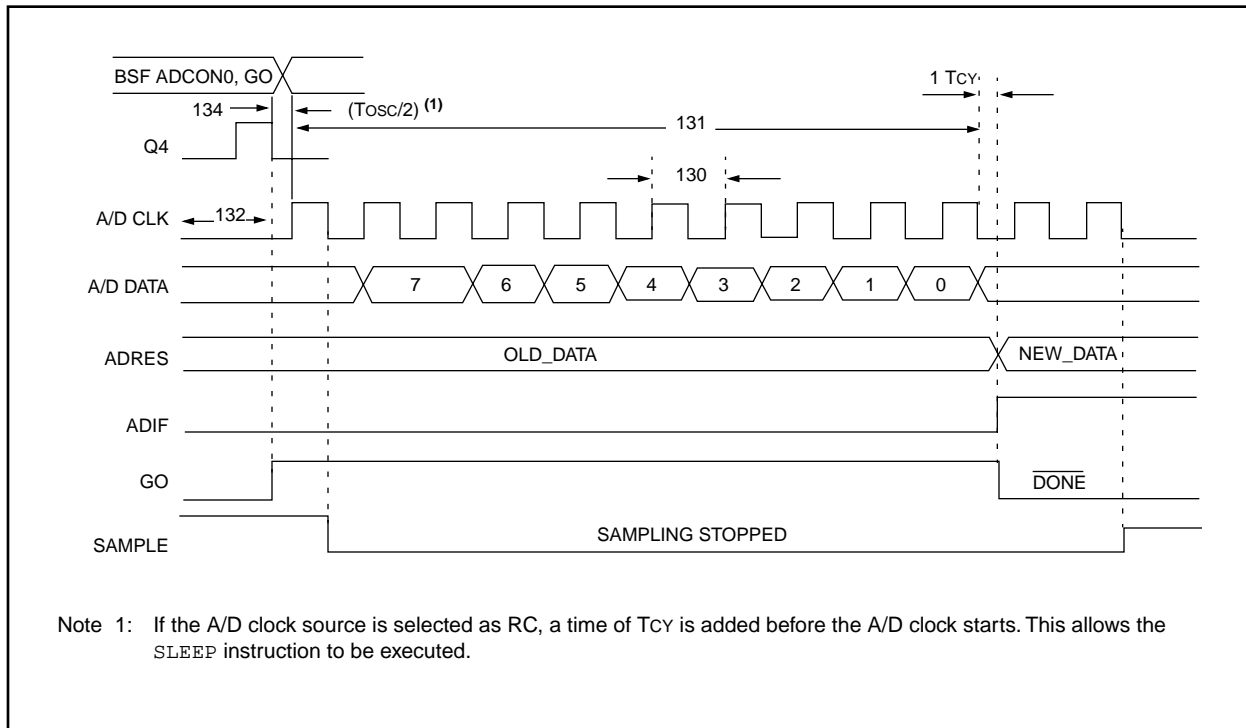


TABLE 18-14: A/D CONVERSION REQUIREMENTS

Param No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
130	TAD	A/D clock period	PIC16C73/74	1.6	—	—	μs	TOSC based, VREF ≥ 3.0V
			PIC16LC73/74	2.0	—	—	μs	TOSC based, VREF full range
			PIC16C73/74	2.0	4.0	6.0	μs	A/D RC Mode
			PIC16LC73/74	3.0	6.0	9.0	μs	A/D RC Mode
131	TCNV	Conversion time (not including S/H time) (Note 1)		—	9.5	—	TAD	
132	TACQ	Acquisition time		Note 2	20	—	μs	The minimum time is the amplifier settling time. This may be used if the "new" input voltage has not changed by more than 1 LSb (i.e., 20 mV @ 5.12V) from the last sampled voltage (as stated on CHOLD).
				5*	—	—	μs	
134	TGO	Q4 to A/D clock start		—	TOSC/2 §	—	—	If the A/D clock source is selected as RC, a time of T _{CY} is added before the A/D clock starts. This allows the SLEEP instruction to be executed.
135	Tswc	Switching from convert → sample time		1.5 §	—	—	TAD	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

§ This specification ensured by design.

Note 1: ADRES register may be read on the following T_{CY} cycle.

2: See Section 13.1 for min conditions.

TABLE 19-13: A/D CONVERTER CHARACTERISTICS:

PIC16C73A/74A-04 (Commercial, Industrial, Extended)
PIC16C73A/74A-10 (Commercial, Industrial, Extended)
PIC16C73A/74A-20 (Commercial, Industrial, Extended)
PIC16LC73A/74A-04 (Commercial, Industrial)

Param No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
A01	NR	Resolution	—	—	8-bits	bit	$V_{REF} = V_{DD} = 5.12V$, $V_{SS} \leq V_{AIN} \leq V_{REF}$
A02	EABS	Total Absolute error	—	—	$< \pm 1$	LSb	$V_{REF} = V_{DD} = 5.12V$, $V_{SS} \leq V_{AIN} \leq V_{REF}$
A03	EIL	Integral linearity error	—	—	$< \pm 1$	LSb	$V_{REF} = V_{DD} = 5.12V$, $V_{SS} \leq V_{AIN} \leq V_{REF}$
A04	EDL	Differential linearity error	—	—	$< \pm 1$	LSb	$V_{REF} = V_{DD} = 5.12V$, $V_{SS} \leq V_{AIN} \leq V_{REF}$
A05	EFS	Full scale error	—	—	$< \pm 1$	LSb	$V_{REF} = V_{DD} = 5.12V$, $V_{SS} \leq V_{AIN} \leq V_{REF}$
A06	EOFF	Offset error	—	—	$< \pm 1$	LSb	$V_{REF} = V_{DD} = 5.12V$, $V_{SS} \leq V_{AIN} \leq V_{REF}$
A10	—	Monotonicity	—	guaranteed	—	—	$V_{SS} \leq V_{AIN} \leq V_{REF}$
A20	VREF	Reference voltage	3.0V	—	$V_{DD} + 0.3$	V	
A25	VAIN	Analog input voltage	$V_{SS} - 0.3$	—	$V_{REF} + 0.3$	V	
A30	ZAIN	Recommended impedance of analog voltage source	—	—	10.0	k Ω	
A40	IAD	A/D conversion current (VDD)	PIC16C73A/74A	—	180	—	μA Average current consumption when A/D is on. (Note 1)
			PIC16LC73A/74A	—	90	—	
A50	IREF	VREF input current (Note 2)	10	—	1000	μA	During VAIN acquisition. Based on differential of VHOLD to VAIN to charge CHOLD, see Section 13.1.
			—	—	10	μA	During A/D Conversion cycle

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: When A/D is off, it will not consume any current other than minor leakage current.

The power-down current spec includes any such leakage from the A/D module.

2: VREF current is from RA3 pin or VDD pin, whichever is selected as reference input.

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Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended, $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial and $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial Operating voltage V_{DD} range as described in DC spec Section 20.1 and Section 20.2.							
DC CHARACTERISTICS							
Param No.	Characteristic	Sym	Min	Typ †	Max	Units	Conditions
D090	Output High Voltage I/O ports (Note 3)	V_{OH}	$V_{DD} - 0.7$	-	-	V	$I_{OH} = -3.0\text{ mA}$, $V_{DD} = 4.5\text{V}$, -40°C to $+85^{\circ}\text{C}$ $I_{OH} = -2.5\text{ mA}$, $V_{DD} = 4.5\text{V}$, -40°C to $+125^{\circ}\text{C}$ $I_{OH} = -1.3\text{ mA}$, $V_{DD} = 4.5\text{V}$, -40°C to $+85^{\circ}\text{C}$ $I_{OH} = -1.0\text{ mA}$, $V_{DD} = 4.5\text{V}$, -40°C to $+125^{\circ}\text{C}$
D090A			$V_{DD} - 0.7$	-	-	V	
D092	OSC2/CLKOUT (RC osc config)		$V_{DD} - 0.7$	-	-	V	
D092A			$V_{DD} - 0.7$	-	-	V	
D150*	Open-Drain High Voltage	V_{OD}	-	-	14	V	RA4 pin
Capacitive Loading Specs on Output Pins							
D100	OSC2 pin	C_{OSC2}	-	-	15	pF	In XT, HS and LP modes when external clock is used to drive OSC1.
D101	All I/O pins and OSC2 (in RC mode)	C_{IO}	-	-	50	pF	
D102	SCL, SDA in I ² C mode	CB	-	-	400	pF	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

- Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C7X be driven with external clock in RC mode.
- 2: The leakage current on the $\overline{\text{MCLR}}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.
- 3: Negative current is defined as current sourced by the pin.

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Applicable Devices 72 73 73A 74 74A 76 77

20.5 Timing Diagrams and Specifications

FIGURE 20-2: EXTERNAL CLOCK TIMING

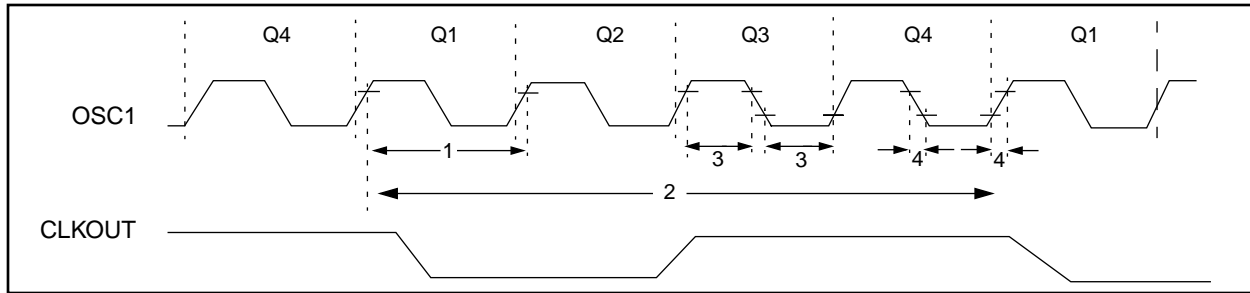


TABLE 20-2: EXTERNAL CLOCK TIMING REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
	Fosc	External CLKIN Frequency (Note 1)	DC	—	4	MHz	XT and RC osc mode
			DC	—	4	MHz	HS osc mode (-04)
			DC	—	10	MHz	HS osc mode (-10)
			DC	—	20	MHz	HS osc mode (-20)
			DC	—	200	kHz	LP osc mode
		Oscillator Frequency (Note 1)	DC	—	4	MHz	RC osc mode
			0.1	—	4	MHz	XT osc mode
			4	—	20	MHz	HS osc mode
			5	—	200	kHz	LP osc mode
	1	External CLKIN Period (Note 1)	250	—	—	ns	XT and RC osc mode
			250	—	—	ns	HS osc mode (-04)
			100	—	—	ns	HS osc mode (-10)
			50	—	—	ns	HS osc mode (-20)
			5	—	—	μs	LP osc mode
		Oscillator Period (Note 1)	250	—	—	ns	RC osc mode
			250	—	10,000	ns	XT osc mode
			250	—	250	ns	HS osc mode (-04)
			100	—	250	ns	HS osc mode (-10)
			50	—	250	ns	HS osc mode (-20)
2	Tcy	Instruction Cycle Time (Note 1)	200	Tcy	DC	ns	Tcy = 4/Fosc
3	TosL, TosH	External Clock in (OSC1) High or Low Time	100	—	—	ns	XT oscillator
			2.5	—	—	μs	LP oscillator
			15	—	—	ns	HS oscillator
4	TosR, TosF	External Clock in (OSC1) Rise or Fall Time	—	—	25	ns	XT oscillator
			—	—	50	ns	LP oscillator
			—	—	15	ns	HS oscillator

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (Tcy) equals four times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKIN pin. When an external clock input is used, the "Max." cycle time limit is "DC" (no clock) for all devices.

FIGURE 20-3: CLKOUT AND I/O TIMING

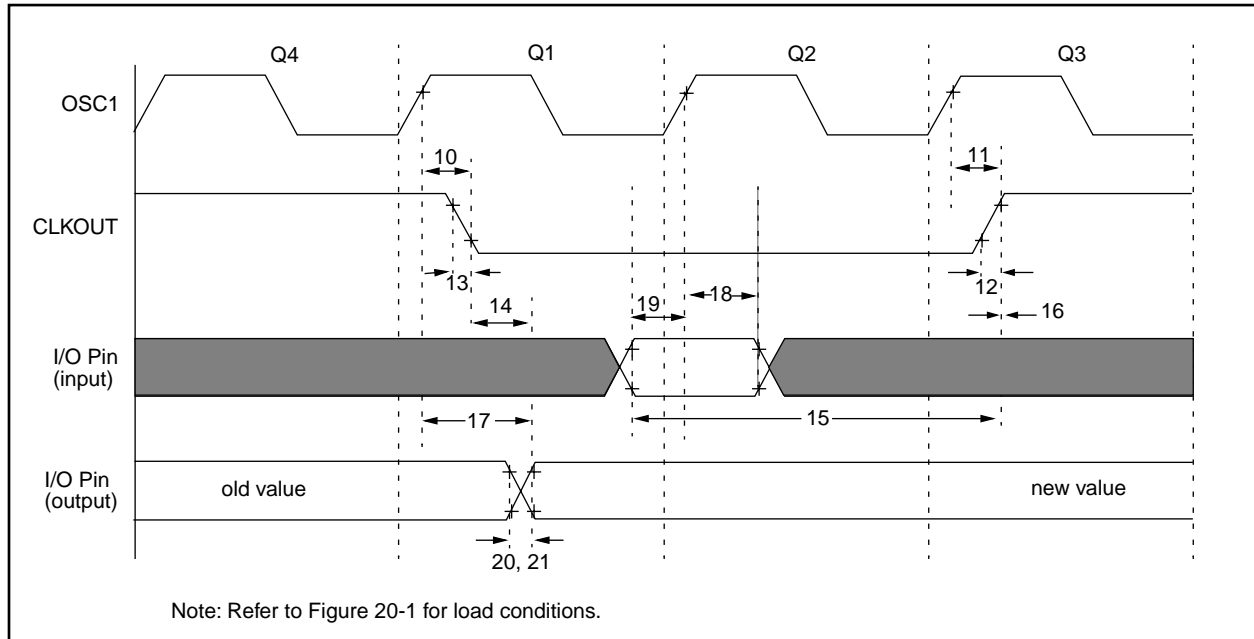


TABLE 20-3: CLKOUT AND I/O TIMING REQUIREMENTS

Param No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
10*	TosH2ckL	OSC1↑ to CLKOUT↓	—	75	200	ns	Note 1
11*	TosH2ckH	OSC1↑ to CLKOUT↑	—	75	200	ns	Note 1
12*	TckR	CLKOUT rise time	—	35	100	ns	Note 1
13*	TckF	CLKOUT fall time	—	35	100	ns	Note 1
14*	TckL2ioV	CLKOUT ↓ to Port out valid	—	—	0.5T _{CY} + 20	ns	Note 1
15*	TioV2ckH	Port in valid before CLKOUT ↑	Tosc + 200	—	—	ns	Note 1
16*	TckH2iol	Port in hold after CLKOUT ↑	0	—	—	ns	Note 1
17*	TosH2ioV	OSC1↑ (Q1 cycle) to Port out valid	—	50	150	ns	
18*	TosH2iol	OSC1↑ (Q2 cycle) to Port input invalid (I/O in hold time)	PIC16C76/77	100	—	—	ns
			PIC16LC76/77	200	—	—	ns
19*	TioV2osH	Port input valid to OSC1↑ (I/O in setup time)	0	—	—	ns	
20*	TioR	Port output rise time	PIC16C76/77	—	10	40	ns
			PIC16LC76/77	—	—	80	ns
21*	TioF	Port output fall time	PIC16C76/77	—	10	40	ns
			PIC16LC76/77	—	—	80	ns
22††*	Tinp	INT pin high or low time	T _{CY}	—	—	ns	
23††*	Trbp	RB7:RB4 change INT high or low time	T _{CY}	—	—	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

†† These parameters are asynchronous events not related to any internal clock edges.

Note 1: Measurements are taken in RC Mode where CLKOUT output is 4 x T_{OSC}.

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